

Application No. 10/065,010  
Filed: September 12, 2002  
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Examiner: L. Cruz  
Art Unit: 2841

### Claim Amendments

1. (Currently Amended) An integrated circuit package device having a plurality of contact points, wherein the plurality of contact points ~~of said at least one integrated circuit package device circuit board~~ includes an inner portion of said contact points and an outer portion of said contact points, the integrated circuit package device comprising at least one of the following:

(i) ~~one or more~~ a majority of power supply contacts configured substantially in an extremity of said outer portion of said integrated circuit package device;

(ii) ~~one or more~~ a majority of timing or frequency contacts configured substantially in said outer portion of said integrated circuit package device; and

(iii) ~~one or more~~ ground contacts configured substantially in said inner portion of said integrated circuit package device; and

(iv) ~~one or more~~ a majority of data or high speed signal contacts configured substantially in an inner side of said inner-outer portion of said integrated circuit package device.

2. (Currently Amended) The integrated circuit package device according to Claim 1, wherein ~~the~~ ground contacts are further provided along a bisectonal axis, through said outer portion ~~of contacts~~ to facilitate a ground path from outside an area of the integrated circuit package device to said inner portion.

3. (Original) The integrated circuit package device according to Claim 1, wherein said inner portion is formed substantially of ground contact points to effect a ground plane.

4. (Currently Amended) The integrated circuit package device according to Claim 1, wherein, for one or more ~~of said signals~~ associated with (i) to (iviii), all of said respective contacts ~~of said integrated circuit~~ are configured in the respective manner described in one or more of (i) to (iviii).

5. (Currently Amended) A printed circuit board having a plurality of tracks for operably coupling electrical signals to a plurality of contact points of at least one

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integrated circuit package device, wherein the plurality of contact points ~~of said at least one integrated circuit package device circuit board~~ includes an inner portion of contact points and an outer portion of contact points, the printed circuit board comprising at least one of the following:

(i) ~~one or more~~ a majority of power supply contacts configured substantially in an extremity of said outer portion ~~of said integrated circuit package device;~~

(ii) ~~one or more~~ a majority of timing or frequency contacts configured substantially in said outer portion ~~of said integrated circuit package device; and~~

(iii) ~~one or more~~ ground contacts configured substantially in said inner portion of said integrated circuit package device; and

(iv) ~~one or more~~ a majority of data or high speed signal contacts configured substantially in an inner side of said inner-outer ~~portion of said integrated circuit package device.~~

6. (Currently Amended) The printed circuit board according to Claim 5, wherein the ground contacts are further provided along a bisectonal axis, through said outer portion ~~of contacts to facilitate a ground path from outside an area of the integrated circuit package device to said inner portion.~~

7. (Original) The printed circuit board according to Claim 5, wherein said inner portion is formed substantially of ground contact points to effect a ground plane.

8. (Currently Amended) The printed circuit board according to Claim 5, wherein, for one or more ~~of said signals associated with (i) to (iviii)~~, all of said respective contacts of said integrated circuit package device are configured in the respective manner described in one or more of (i) to (iiiiv).

9. (Currently Amended) An electrical or electronic device comprising the integrated circuit package device according to claim 5.

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**Claim Amendments**

10. (New) The integrated circuit package device according to claim 1 further comprising at least one ground contact configured substantially in said inner portion.
11. (New) The printed circuit board according to claim 5 further comprising at least one ground contact configured substantially in said inner portion.
12. (New) The integrated circuit package device according to claim 1 wherein the inner portion and the outer portion are two distinct regions separated by a space.
13. (New) The printed circuit board according to claim 5 wherein the inner portion and the outer portion are two distinct regions separated by a space.